

## AMENDMENTS TO THE CLAIMS

Please amend the claims as set forth in the following listing. This listing of claims will replace all prior versions, and listings, of claims for the present application:

Claims 1-54 (Canceled).

55.(Currently Amended)      A process for using a photo-definable layer in a negative mask scheme to manufacture a semiconductor device, comprising:

forming over a substrate a photo-definable layer that is convertible to an insulative material;

exposing selected portions of said photo-definable layer to electro-magnetic radiation in a negative pattern scheme to convert said selected portions to an insulative material;

removing non-exposed portions of said photo-definable layer with an etch process that is selective to exposed portions of said photo-definable layer;

using said exposed portions of said photo-definable layer as a patterned etch mask for further processing steps;~~and;~~

leaving said exposed portions of said photo-definable layer as an insulative layer within said semiconductor device;~~and~~

converting said insulative layer to an oxide layer through exposure to an oxygen plasma.

56.(Previously Presented)      The process of claim 55, wherein said photo-definable layer comprises an organosilicon resist.

57. (Previously Presented)      The process of claim 56, wherein said photo-definable layer comprises plasma polymerized methylsilane (PPMS) and said insulative material comprises photo-oxidized siloxane (PPMSO).

58. (Canceled)

59.(Currently Amended) A semiconductor device formed using a photo-definable layer in a negative mask scheme, comprising:

a substrate;

at least one feature formed on said substrate by converting selected portions of a photo-definable layer to an insulative material through exposure to electro-magnetic radiation in a negative mask scheme, by using exposed portions of said photo-definable layer as an etch mask to form said at least one feature, and by leaving said exposed portions of said photo-definable layer on said substrate as an insulative layer; and

an oxide layer on said substrate, wherein said insulative layer is converted to said oxide layer through exposure to an oxygen plasma.

60. (Previously Presented) The semiconductor memory device of claim 59, wherein said photo-definable layer comprises an organosilicon resist.

61. (Previously Presented) The semiconductor memory device of claim 60, wherein said photo-definable layer comprises plasma polymerized methylsilane (PPMS).

Claims 62-75 (Canceled).

76. (Previously Presented) A process of using a photo-definable layer in a Damascene process to create a patterned structure, comprising:

forming on a substrate a photo-definable layer that is convertible to an insulative material;

exposing selected portions of said photo-definable layer to electro-magnetic radiation to convert said selected portions to an insulative material;

removing non-exposed portions of said photo-definable layer with an etch process that is selective to exposed portions of said photo-definable layer to form a desired pattern within said exposed portions of said photo-definable layer;

leaving said exposed portions of said photo-definable layer on said substrate as an insulative layer; and  
converting said insulative layer to an oxide layer through exposure to an oxygen plasma.

77. (Previously Presented) The process of claim 76, wherein said photo-definable layer comprises an organosilicon resist.

78. (Previously Presented) The process of claim 77, wherein said photo-definable layer comprises plasma polymerized methylsilane (PPMS) and said insulative material comprises photo-oxidized siloxane (PPMSO).

79. (Previously Presented) The process of claim 78, further comprising consolidating said oxide layer with an anneal.

80. (Previously Presented) The process of claim 79, further comprising depositing a conductive material within said pattern.

81. (Previously Presented) The process of claim 80, wherein said conductive material forms an interconnect structure within a semiconductor memory device.

82. (Previously Presented) The process of claim 76, wherein said exposing step is performed by irradiating said selected portions of said photo-definable layer with ultraviolet light in the presence oxygen.

83. (Previously Presented) The process of claim 82, wherein said non-exposed portions of said photo-definable layer are removed using a chlorine-based or a bromine-based plasma etch.

84.(Currently Amended) A conductive interconnect structure within a semiconductor device formed using a photo-definable layer, comprising:  
a substrate;

a patterned ~~insulative~~ oxide layer on said substrate formed by converting selected portions of a photo-definable layer to an insulative material through exposure to electro-magnetic radiation in a negative mask scheme, by removing non-exposed portions of said photo-definable layer to form a pattern within said photo-definable layer, ~~and~~ by leaving said exposed portions of said photo-definable layer as ~~said an~~ patterned insulative layer, and by converting said patterned insulative layer to a patterned oxide layer through exposure to an oxygen plasma;  
and  
a conductive layer inlaid within said patterned ~~insulative~~ oxide layer.

85. (Previously Presented) The semiconductor structure of claim 84, wherein said photo-definable layer comprises an organosilicon resist.

86. (Previously Presented) The semiconductor structure of claim 85, wherein said photo-definable layer comprises plasma polymerized methylsilane (PPMS).

87. (Previously Presented) The semiconductor structure of claim 84, wherein said conductive layer forms an interconnect structure within a semiconductor memory device.

Claims 88-100 (Canceled).